

Thick Film Chip Resistors, Alternate Terminations



MECHANICAL SPECIFICATIONS				
Resistive element	Ruthenium oxide			
Encapsulation	Glass			
Substrate	96 % alumina			
Termination	Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold terminations available.			
Solder finish	Base metallization without a solder finish standard. Hot solder dipped tin/silver or tin/lead/silver solder alloys available.			

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature: - 55 °C to + 150 °C

Moisture Resistance: Less than 0.5 % change when tested

per method 106 of MIL-STD-202

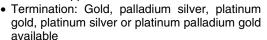
Life: Less than 1 % change when tested per method 108D

(+ 85 °C) of MIL-STD-202

Short Time Overload: Less than $0.5 \% \Delta R$

FEATURES

• Suitable for solderable, epoxy bondable, or wire bondable applications



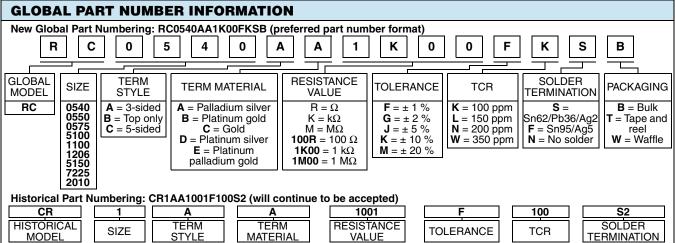


- Multiple styles, termination materials and configurations, allow wide design flexibility
- Non-magnetic terminations
- Flow solderable
- · Custom sizes available
- · Burn-in data available
- · Automatic placement capability
- Available with either wraparound terminations or as a single termination flip chip
- Tape and reel packaging available
- Internationally standardized sizes
- Compliant to RoHS directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition

STANDARD ELECTRICAL SPECIFICATIONS						
GLOBAL MODEL	POWER RATING P ₇₀ °C W	RESISTANCE RANGE ⁽¹⁾ Ω	TOLERANCE ± %	TEMPERATURE COEFFICIENT (2) (- 55 °C to + 150 °C) ± ppm/°C	MAXIMUM WORKING VOLTAGE ⁽³⁾ V	
RC0540	0.100	10 to 500k	1, 2, 5, 10, 20	100	40	
RC0550	0.100	10 to 500k	1, 2, 5, 10, 20	100	50	
RC0575	0.200	10 to 1M	1, 2, 5, 10, 20	100	70	
RC5100	0.250	10 to 1M	1, 2, 5, 10, 20	100	100	
RC1100	0.450	10 to 1M	1, 2, 5, 10, 20	100	100	
RC1206	0.300	10 to 1M	1, 2, 5, 10, 20	100	100	
RC5150	0.325	10 to 1M	1, 2, 5, 10, 20	100	125	
RC7225	0.525	10 to 1M	1, 2, 5, 10, 20	100	200	
RC2010	0.575	10 to 1M	1, 2, 5, 10, 20	100	200	

Notes

- (1) Higher values available. Please consult factory.
- $^{(2)}$ ± 100 ppm/°C standard thru 1 M Ω , ± 200 ppm/°C offered from 1.1 M Ω to 10 M Ω .
- (3) Continuous working voltage shall be $\sqrt{P \times R}$ or maximum working voltage, whichever is less.



Pb containing terminations are not RoHS compliant, exemptions may apply

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DIMENSIONS in inches (millimeters)						
Termination Style A (3-sided wraparound)	Termination Style B (Top conductor only)	Termination Style C (5-sided wraparound)	MODEL	LENGTH (L) (1) ± 0.006 (0.152)	WIDTH (W) (1) ± 0.006 (0.152)	THICKNESS (T) (1) ± 0.005 (0.127)
			RC0540	0.050 (1.27)	0.040 (1.02)	0.020 (0.508)
			RC0550	0.050 (1.27)	0.050 (1.27)	0.020 (0.508)
W ,	W /s	w z	RC0575	0.075 (1.90)	0.050 (1.27)	0.020 (0.508)
	J/ //		RC5100	0.100 (2.54)	0.050 (1.27)	0.020 (0.508)
	Ţ	Ţ ////) ·	RC1100	0.100 (2.54)	0.100 (2.54)	0.020 (0.508)
0.025 [0.635] Max.	0.025 [0.635] Max.	0.025 [0.635] Max.	RC1206	0.125 (3.18)	0.062 (1.57)	0.025 (0.635)
	WIGA.		RC5150	0.150 (3.81)	0.050 (1.27)	0.020 (0.508)
			RC7225	0.225 (5.72)	0.075 (1.90)	0.020 (0.508)
			RC2010	0.200 (5.08)	0.100 (2.54)	0.025 (0.635)

Note
(1) All dimensions are before solder coating.

TYPE	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE/ MATERIAL CODE	SOLDER TERMINATION CODE	
Wire bondable/ solderable		3-sided (wraparound)	AE		
	Platinum palladium gold	Top only (flip chip)	BE	N, F or S ⁽²⁾	
		5-sided (wraparound)	CE		
Wire bondable/ Epoxy bondable		3-sided (wraparound)	AC		
	Gold	Top only (flip chip)	BC	N	
		5-sided (wraparound)	CC		
Epoxy bondable		3-sided (wraparound)	AA		
	Palladium silver (3)	Top only (flip chip)	BA		
		5-sided (wraparound)	CA		
		3-sided (wraparound)	AB		
	Platinum gold	Top only (flip chip)	BB	N	
		5-sided (wraparound)	СВ		
		3-sided (wraparound)	AD		
	Platinum silver	Top only (flip chip)	BD		
		5-sided (wraparound)	CD		

Notes

For technical questions, contact: telresistors@vishay.com Document Number: 68013 Revision: 20-Jul-10

⁽²⁾ Use solder termination N for applications requiring wire bondable mounting, and solder terminations F or S for applications requiring solderable

⁽³⁾ While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver.



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